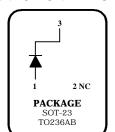


MMBD301

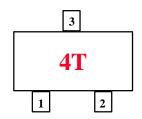
DISCRETE POWER AND SIGNAL TECHNOLOGIES

CONNECTION DIAGRAM



PACKAGE

SOT-23 TO-236AB (Low)



Schottky Barrier Diode

Sourced from Process GD

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

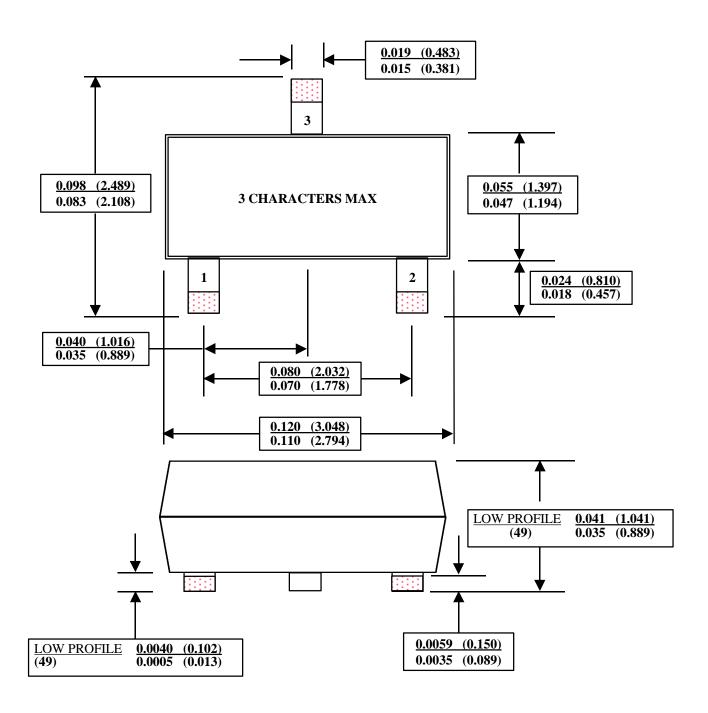
Sym	Parameter	Value	Units	
T _{sta}	Storage Temperature	-55 to +150	οС	
T _J	Operating Junction Temperature	-55 to +125	οС	
W _{iv}	Working Inverse Voltage	25	V	
P _F	Forward Power Dissipation @ T _A = 25°C	200	mW	
	Derate above 25 ^o C	2.0	Mw/ ^o C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

Electrical Characteristics TA = 25°C unless otherwise noted

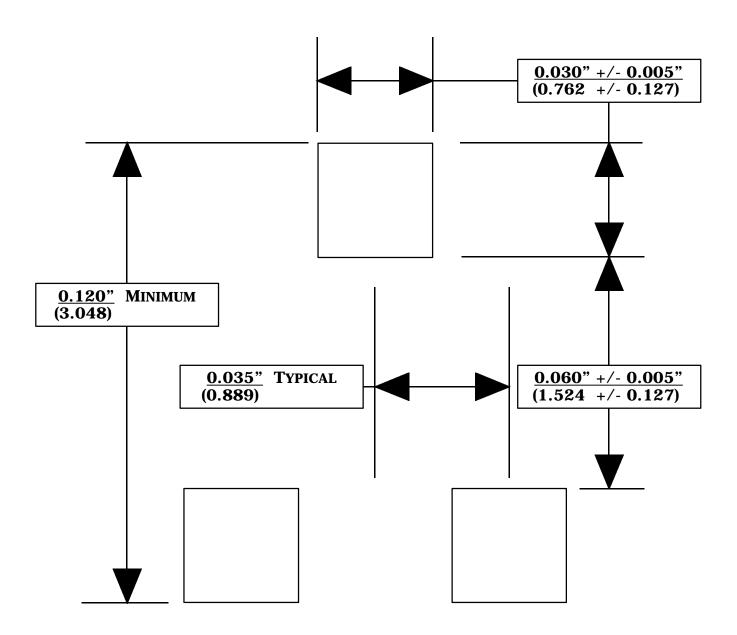
SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B _V Bre	akdown Voltage	30		V	$I_R = 10 \text{ uA}$
I _R Re	verse Leakage		200	nA	V _R = 25 V
V _F For		450 600	mV mV	$I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$	
C _⊤ Ca	pacitance		1.5	pF	$V_{R} = 15 V$ f = 1.0 MHz





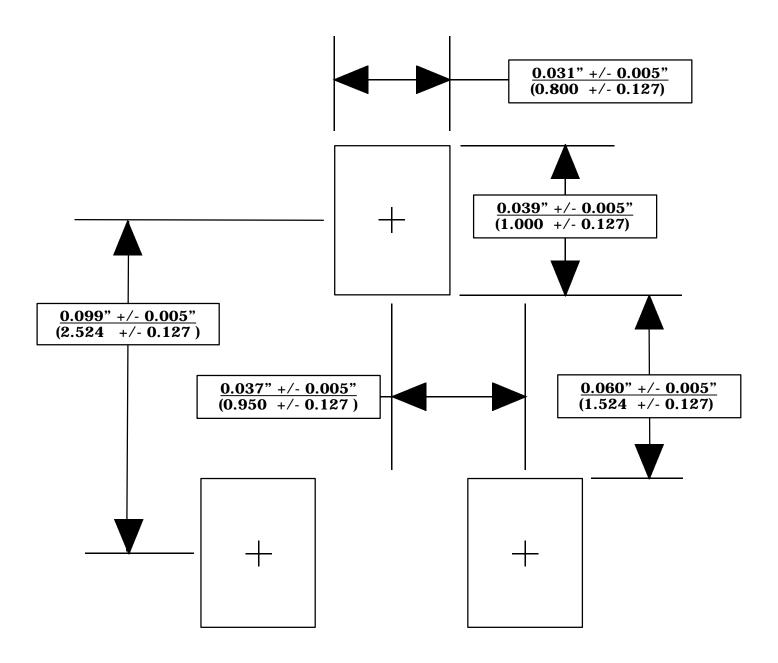
SOT-23 TO-236AB (LOW PROFILE) 22-August-1994



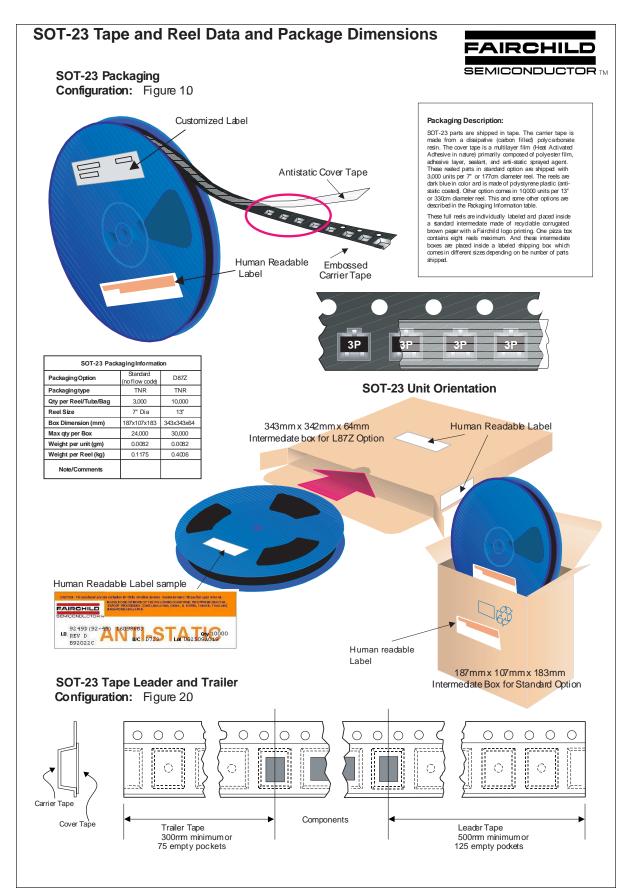


RECOMMENDED SOLDER PADS FOR SOT-23





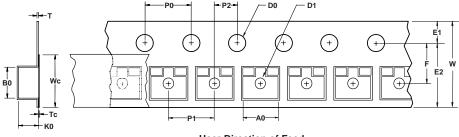
RECOMMENDED SOLDER PADS FOR U.S. & European SOT-23 & Japanese SC-59



SOT-23 Tape and Reel Data and Package Dimensions, continued

SOT-23 Embossed Carrier Tape

Configuration: Figure 3.0



User Direction of Feed

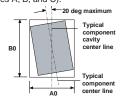
Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)

Component Rotation



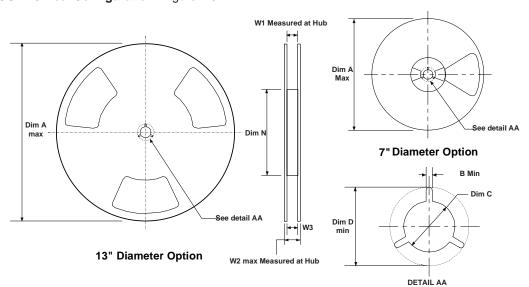
Sketch B (Top View)
Component Rotation



Sketch C (Top View)

Component lateral movement

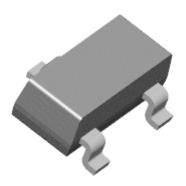
SOT-23 Reel Configuration: Figure 4.0

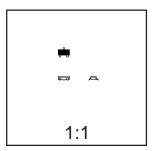


	Dimensions are in inches and millimeters								
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

SOT-23 Tape and Reel Data and Package Dimensions, continued

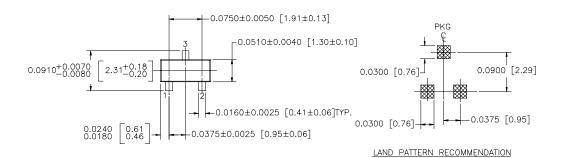
SOT-23 (FS PKG Code 49)

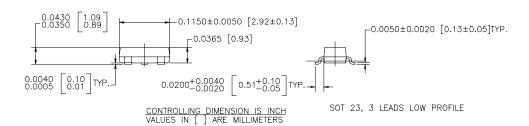




Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082





NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

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